

Amendments to the Claims

1. *(Currently Amended)* An electronic device comprising a free-standing thin film (30), the thin film (30) comprising an alloy of aluminum and at least magnesium.

2. *(Original)* An electronic device as claimed in claim 1, comprising an alloy of aluminum, magnesium and at least one further material.

3. *(Original)* An electronic device as claimed in Claim 2, wherein said at least one further material comprises one or more of copper, manganese, silicon, nickel, chromium, and lithium.

4. *(Currently Amended)* An electronic device as claimed in ~~Claim 1, 2 or 3~~claim 1, wherein the Mg content is between 0.1 and 10 atomic weight per cent.

5. *(Original)* An electronic device as claimed in Claim 3, wherein said one further material comprises copper in an amount between 0.1 and 8 atomic weight per cent.

6. *(Currently Amended)* An electronic device as claimed in ~~Claim 3 or 5~~claim 3, wherein the sum of the contents of magnesium, copper and manganese is between 2.5 and 10 atomic weight per cent.

7. *(Currently Amended)* An electronic device as claimed in ~~Claim 3 or 6~~claim 3, wherein the alloy is chosen from the group of $A1_vMg_wCu_xMn_y$, $A1_vMg_wMn_y$, $A1_vMg_wCu_xSi_{z1}Ni_{z2}$, $A1_vMg_wCu_x$, $A1_vMg_wCu_xSi_{z1}$, $A1_vMg_wCu_xZn_{z3}Cr_{z4}$, $A1_vMg_wCu_xLi_{z5}$, with $80 \leq v \leq 99.8$; and $0.1 \leq w \leq 8.0$, $0.1 \leq x \leq 8.0$, $0.1 \leq y \leq 4.0$ and $z1, z2, z3, z4, z5$ each smaller than 20, and preferably smaller than 5.

8. *(Currently Amended)* A method of manufacturing an electronic device comprising a free-standing thin film (30), the method comprising the steps of:
- providing a mechanical layer of material (12) on a sacrificial release layer (16, 17);

- structuring said mechanical layer ~~(12)~~ to define the film ~~(30)~~; and
- removing said release layer ~~(16, 17)~~ to render said film ~~(30)~~ free-standing. characterized in that said top layer comprises an alloy of aluminum and at least magnesium.

9. *(Currently Amended)*

A method according to claim 8, wherein said release layer ~~(16, 17)~~ is patterned prior to provision of said mechanical layer ~~(12)~~ thereon.